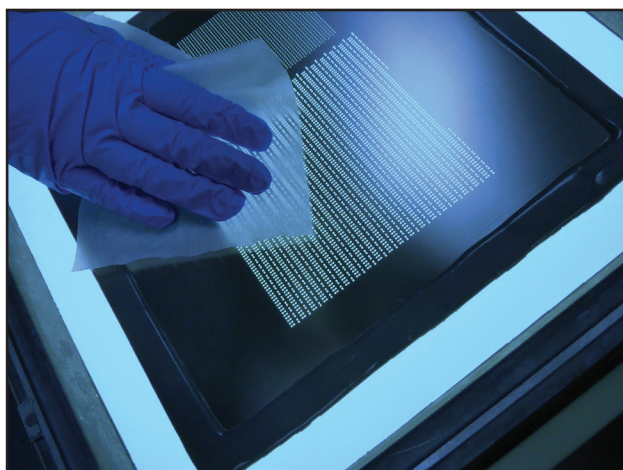


CYBERSOLV® C8882

Understencil Wipe/Stencil Cleaning Solvent

CYBERSOLV C8882 is a fast-acting stencil cleaning solvent designed for the understencil wipe and hand cleaning processes. C8882 instantly dissolves all flux types within the solder paste, including water soluble, rosin and low residue no-clean fluxes.



- **Removes All Flux Types**
- **Fast Drying**
- **Non-Flammable**
- **Does Not Interact or Remove Nano Coatings**
- **Compatible with Wetted components in Automatic Stencil Printers**
- **Effectively Cleans Uncured Chip Bonding Adhesives**
- **Dries Completely - Residue-Free**

PRODUCT PROPERTIES

pH	N/A (Solvent-Based)
FLASH POINT	142°F / 61°C
BOILING POINT	270°F / 132°C
WATER SOLUBLE	Partial
VOC, @ 100%	875.6 g/L

TYPICAL PROCESSES

APPLICATION	Understencil, Hand-held Ultrasonic Cleaner & Manual
CONCENTRATION	100%
TEMPERATURE	Ambient
RINSE	No Rinse Required
DRY	None Required

The above process parameters are recommendations based on extensive testing done in KYZEN's application lab. Your KYZEN sales representative can assist you in optimizing your process parameters.

STORAGE AND HANDLING

- Packaged in Polyethylene Containers
- Store at 5-50°C/41-122°F in Original Container
- Standard Chemical Handling Practices
- Shelf Life of 5 Years, in Sealed Containers of 5 gallons/25 Liters or More

AVAILABILITY

- | | |
|--------------|---------------|
| • 1 Gallon | • 5 Liters* |
| • 5 Gallons | • 25 Liters* |
| • 55 Gallons | • 200 Liters* |

* Liters Available in South Asia and Europe

CYBERSOLV C8882

Understencil Wipe/Stencil Cleaning Solvent



ENVIRONMENTAL, HEALTH AND SAFETY REGULATIONS

CYBERSOLV C8882 is RoHS compliant and Halogen-free in accordance with RoHS Directive (EU) 2015/863 and EN 14582:2016. C8882 has a negligible global warming potential, is not regulated as an Ozone Depleting Chemical in the United States and is not listed as a Hazardous Air Pollutant. Refer to the Safety Data Sheet for more information.

REACH ✓ KYZEN is an ISO 9001:2015 Certified Company

COMPATIBILITY

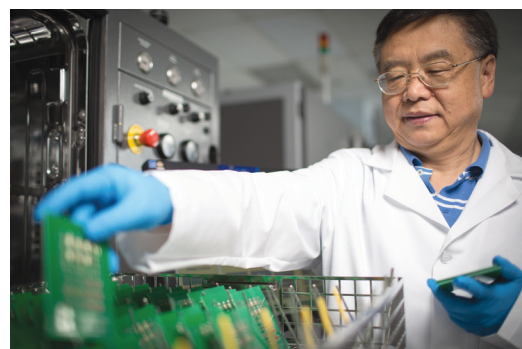
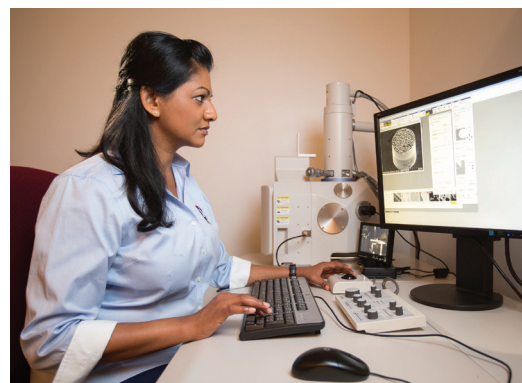
CYBERSOLV C8882 is compatible with all materials commonly used in electronic assembly manufacturing and cleaning processes. For specific compatibility information, please contact your KYZEN representative.

FREE CLEANING TRIALS AND PROCESS OPTIMIZATIONS

KYZEN will conduct complimentary trials at your factory or "risk-free" testing in one of our global applications laboratories in North America, Asia or Europe to ensure you achieve your goal. Increase your yields and product reliability by identifying and tuning the critical parameters of your cleaning process. With our commitment to science and understanding process, KYZEN has the flexibility to simulate and refine any cleaning process.

Each laboratory is fully equipped with an extensive array of cleaning and analytical equipment including:

- Batch Washers
- In-Line Washers
- Ultrasonic Systems
- SUI Systems
- Vapor Degreasers
- GC (TCD and FID)
- Scanning Electron Microscope (SEM)
- Ion Chromatography
- FTIR Spectrophotometer
- Humidity Chamber
- High Powered Microscopes



***Aqueous, Semi-Aqueous and Vapor Phase Chemistries • Process Evaluation and Optimization
Contract Cleaning • Cleanliness Testing • Soil Analysis***

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The information contained herein is based on available data from reliable sources and is accurate to the best of KYZEN Corporation's knowledge at the time of this publication. The user is solely responsible for determining the suitability and completeness of such information for their particular application and for adopting appropriate safety precautions. This data is not to be taken as a warranty or representation for which KYZEN assumes legal or financial responsibility. 051021

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